

Electro-deposition of Pd on Carbon paper and Ni foam via surface limited redox-replacement reaction for oxygen reduction reaction

Mmalewane Modibedi, Eldah Louw, MKhulu Mathe, Kenneth Ozoemena

mmodibedi@csir.co.za



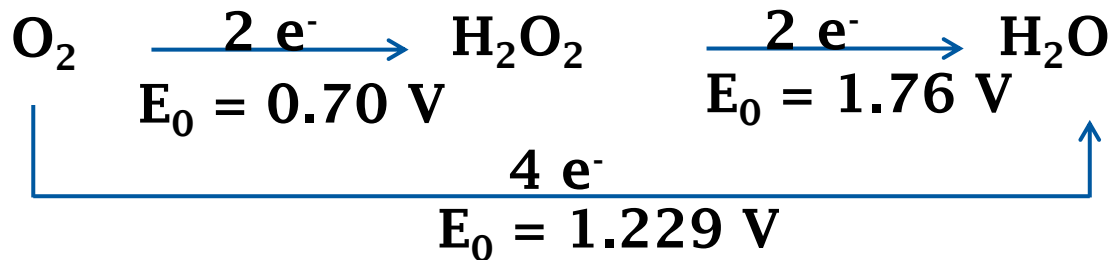
our future through science

Outline of the presentation

- Introduction: Oxygen reduction reaction (ORR)
- Fuel cells: Proton exchange membrane (PEM) and Anion exchange membrane (AEM)
- Electrocatalysts: Preparation
- Electrocatalysts: Characterisation
- Electrocatalysts: Electrochemical evaluation
 - Acid electrolyte
 - Alkaline electrolyte
- Conclusions and Future Work

1. Oxygen reduction reaction (ORR)

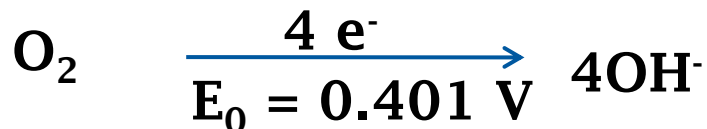
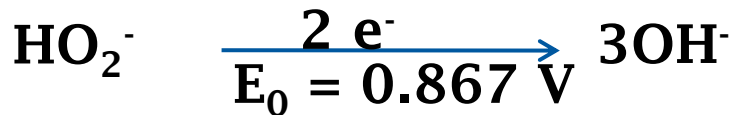
- ORR is most important reaction in life processes and energy converting systems: **Fuel cells**, Sensors
- ORR pathways in aqueous solutions:



**Acid aqueous
electrolyte**

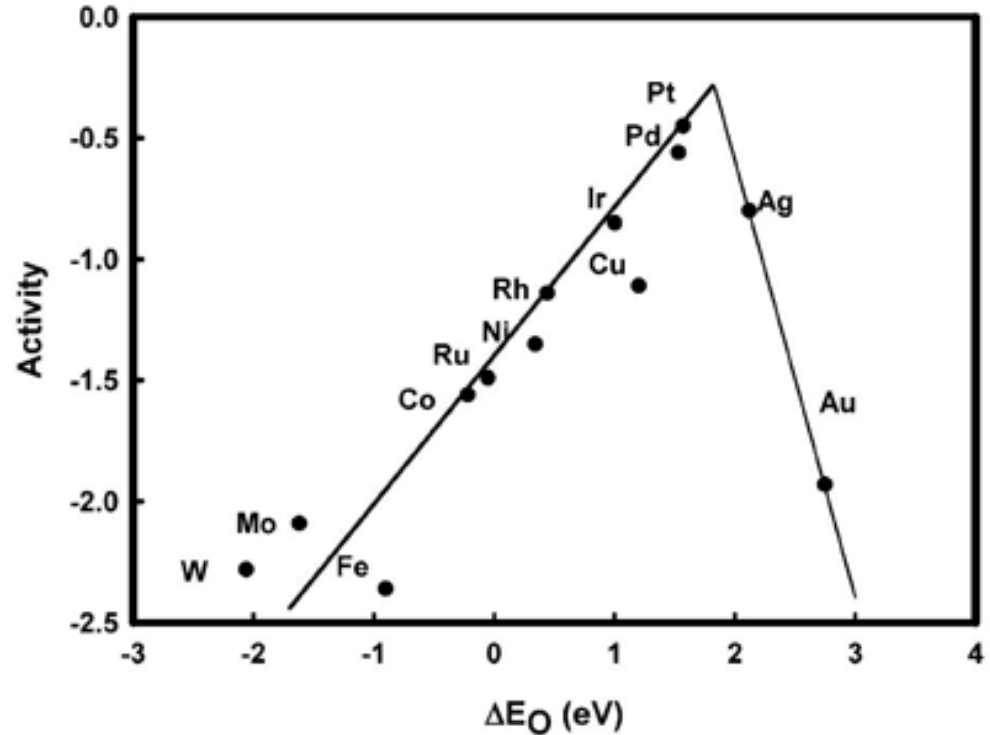
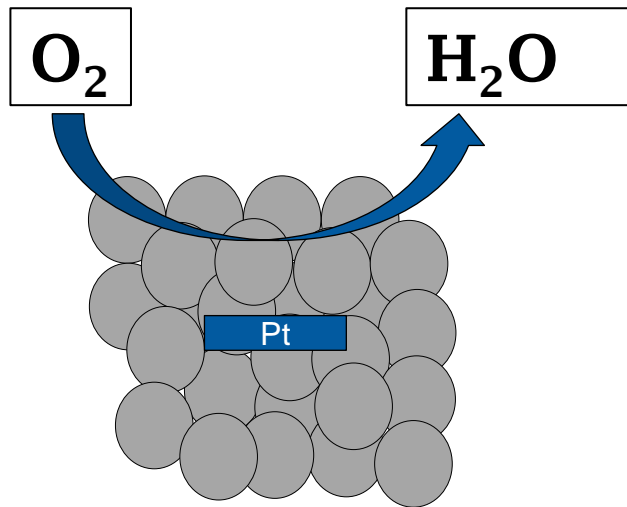


**Alkaline aqueous
electrolyte**



1. ORR Catalysts

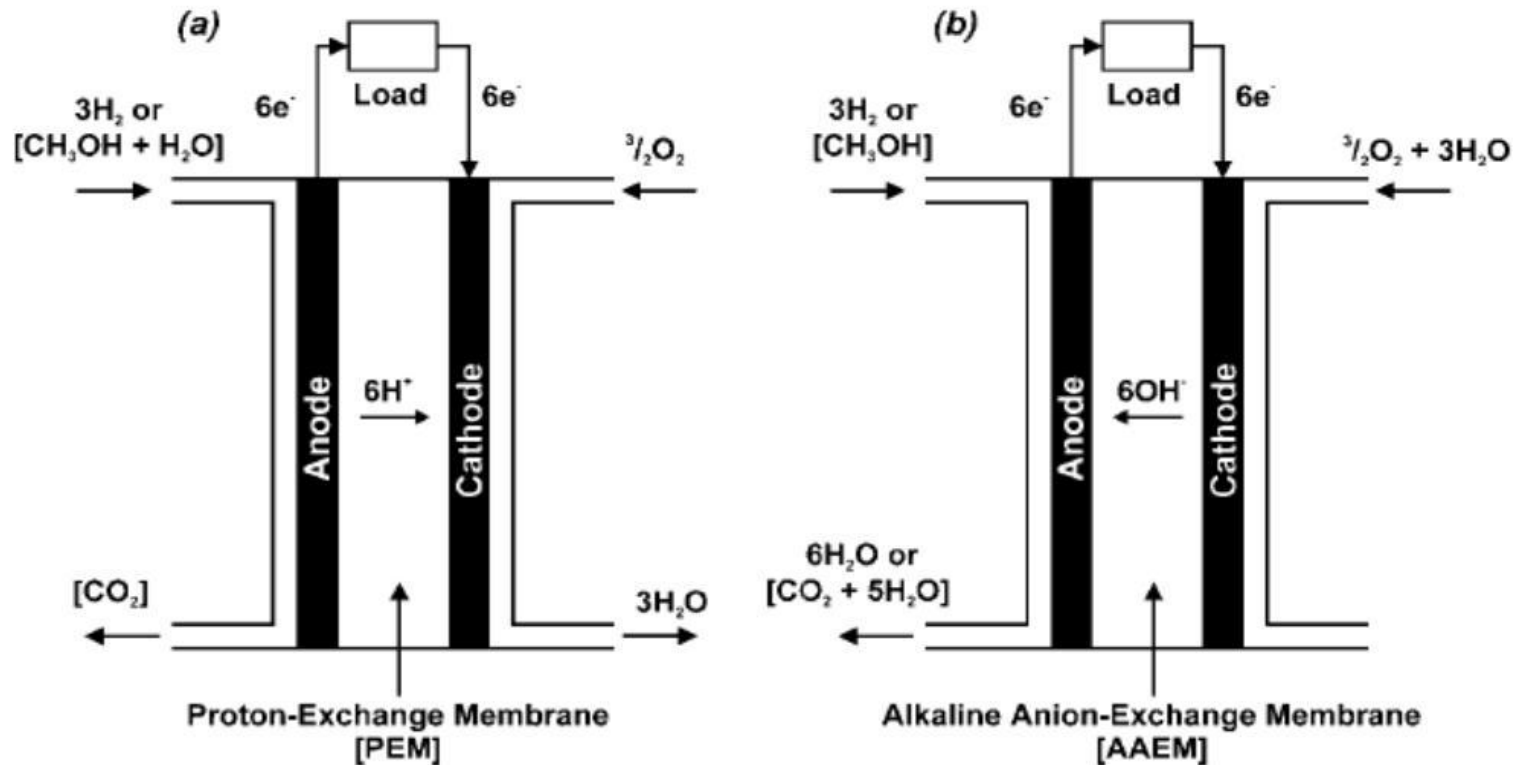
- ORR kinetics is very slow
 - Catalyst is essential
- Pt-based catalysts
- Alternative catalysts
 - Less expensive than Pt



Oxygen reduction activity on various transition metal electrodes as a function of the oxygen binding energy from DFT calculations.

2. Fuel Cells

2.1 Low temperature PEMFC, DMFC, AEMFC



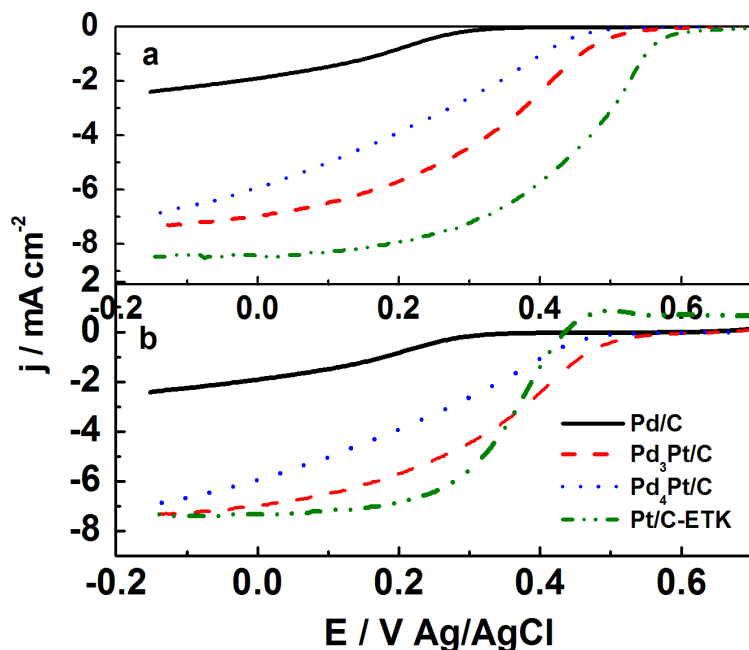
Why AAEM?

- Catalysts: use non-noble metals, faster kinetics of oxygen reduction and alcohol oxidation
- Membrane: reduced or no alcohol crossover

3. Electrocatalysts

3.1 Preparation methods

- Sonochemistry
 - Pt, Pd₃Pt on Carbon black



- Microwave-assisted alcohol reduction

- Ru on N-doped CNTs

Electrode	Onset potential V	No of electron transferred at (1500 rpm, -0.30V)	Limiting current density (mA/cm ²)
N-CNTs	-0.166	2.4	-2.95
2Ru/N-CNTs	-0.158	3.9	-4.76
5Ru/N-CNTs	-0.153	3.7	-4.54
10Ru/N-CNTs	-0.148	3.2	-3.66

3. Electrocatalysts

3.1.1 Electrochemical atomic layer technique (ECALD):

Definition:

alternated electrodeposition of atomic layers of elements on a substrate, employing under-potential deposition (UPD) in which one element deposits onto another element at a voltage prior to that necessary to deposit the element onto itself

Advantages:

- ambient temperature,
- use small concentrations of precursor solutions,
- optimized solutions and potential separately

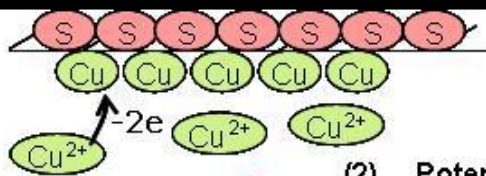
Offers **atomic layer control**- fundamental for controlled growth processes



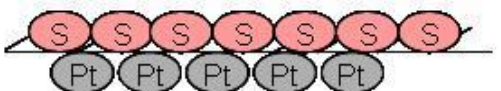
Sequential electrodeposition coupled to Surface-limited Redox-replacement reactions: Synthesis of multilayered Pt electrocatalyst



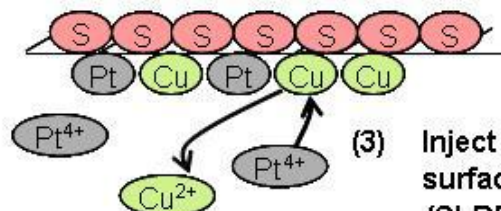
(1) Clean substrate with blank electrolyte (BE);
Inject Cu^{2+} solution at $E \gg E_{\text{Cu-Cu}^{2+}}$



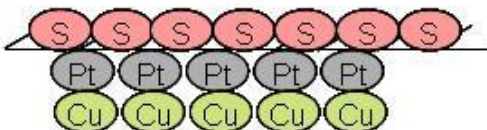
(2) Potentiostatic electrodeposition at $-E_{\text{dep}} > E_{\text{Cu-Cu}^{2+}}$ (Underpotential Deposition (UPD)) or $-E_{\text{dep}} < E_{\text{Cu-Cu}^{2+}}$ (small Overpotential Deposition (OPD)) - to produce sacrificial Cu adlayer on active sites of the substrate; Rinse with BE



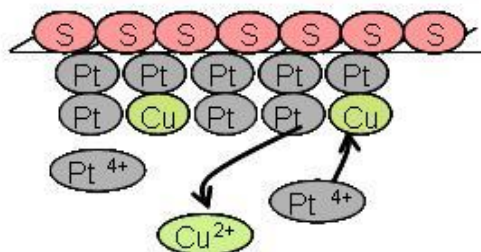
(4) Pt nanodeposit on substrate;
Rinse with BE and inject Cu^{2+} solution at $E \gg E_{\text{Cu-Cu}^{2+}}$



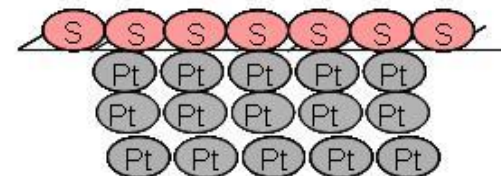
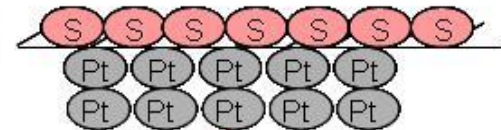
(3) Inject H_2PtCl_6 solution and allow surface-limited redox-replacement (SLRR) of Cu by Pt at open circuit (OC)



(5) Potentiostatic electrodeposition at $-E_{\text{dep}}$ to produce sacrificial Cu adlayer on active sites on Pt adlayers; Rinse with BE



(6) Inject H_2PtCl_6 solution and allow surface-limited redox-replacement (SLRR) of Cu by Pt at OC



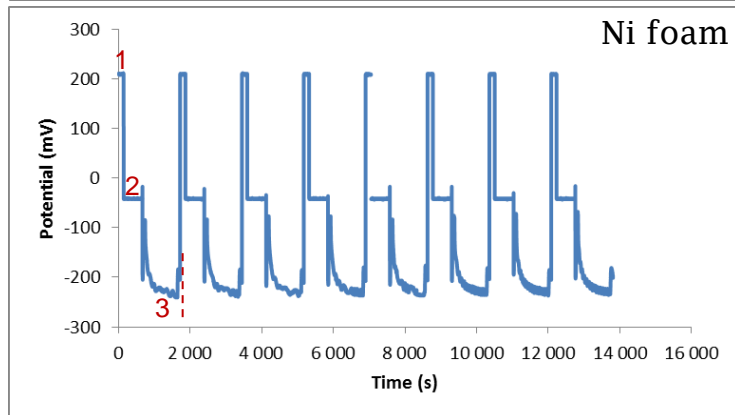
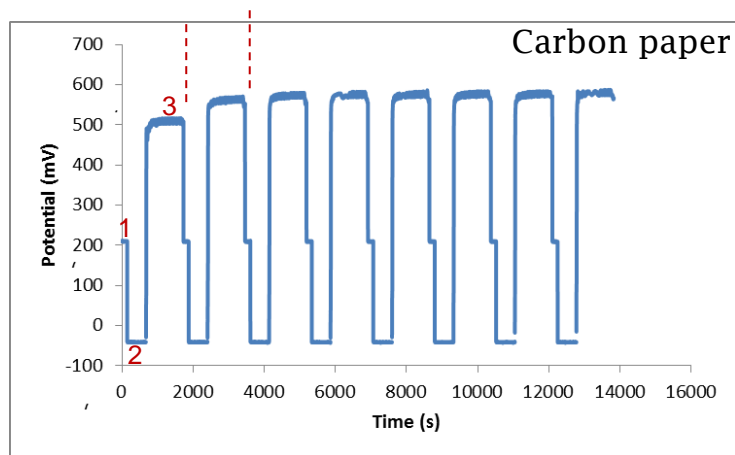
3.1.1 ECALD cont'd:

Noble-Metal: **Pd**

Substrates: **Carbon paper, Ni foam**

Repeat cycles 1X, 4X, 8X: **8X, Small OPD**

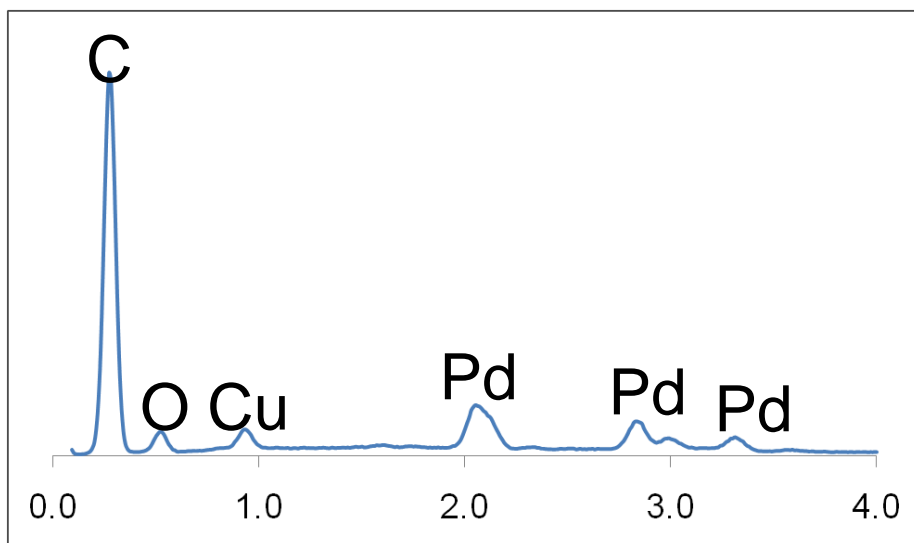
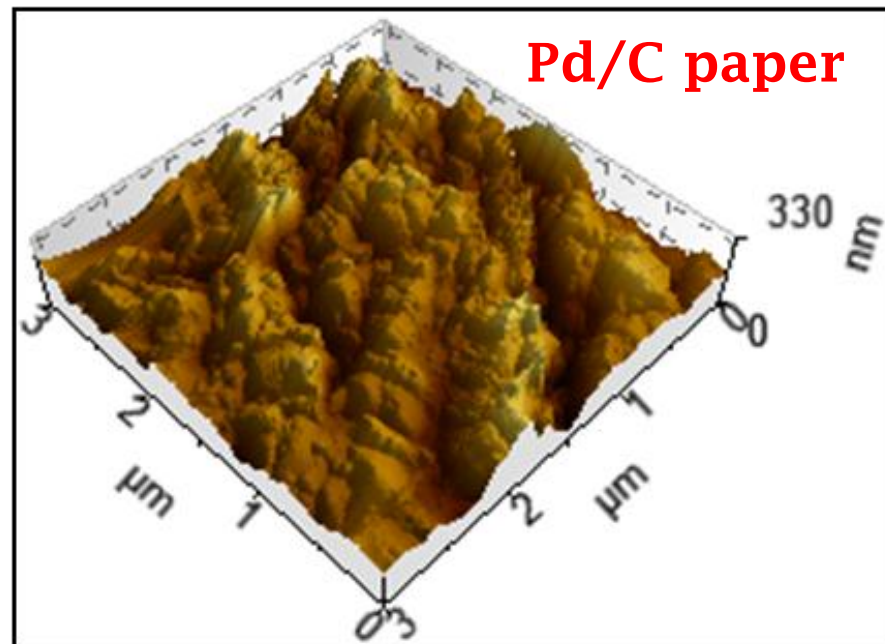
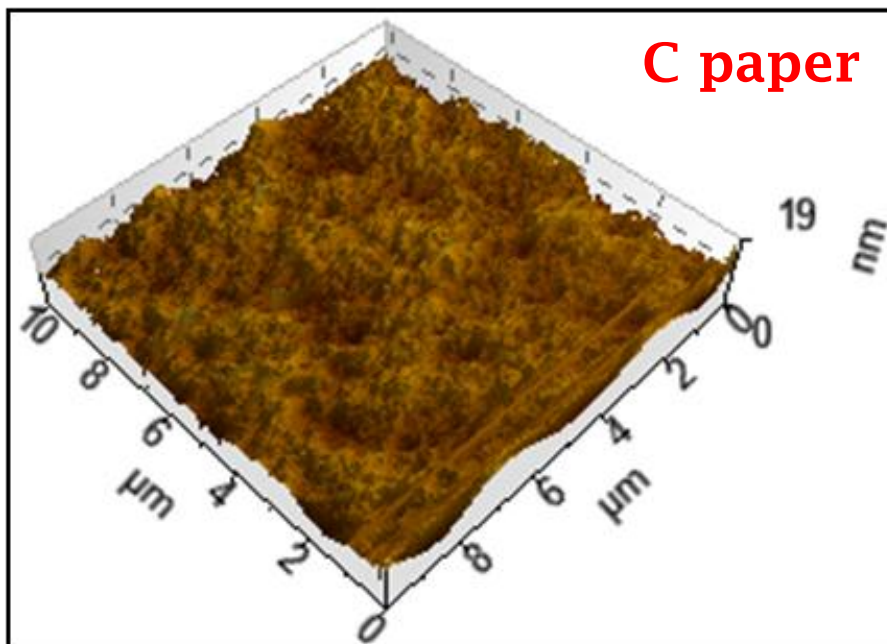
- **Cu(s) deposition occurs through kinetically controlled 3D nucleation**



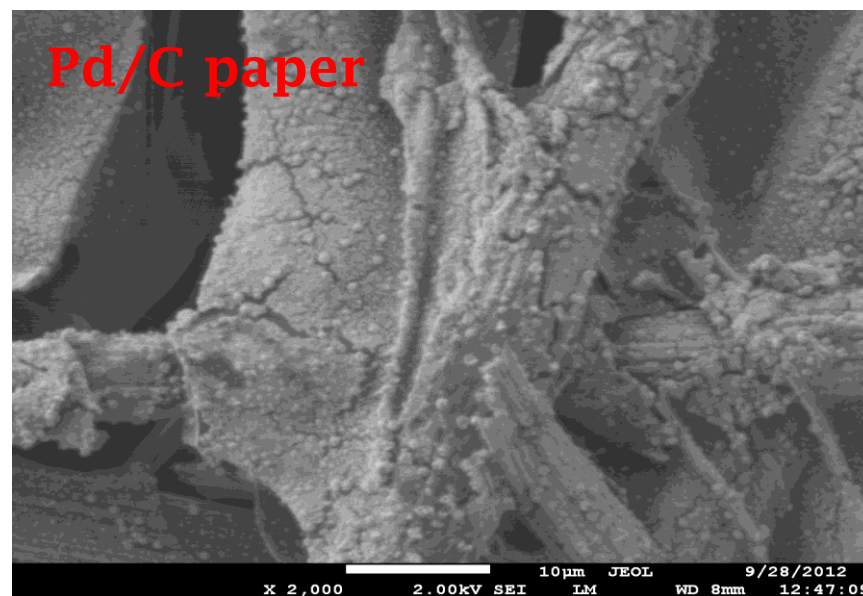
1. Rinse cell with BE at 0.2V, rinse with Cu^{2+} solution
2. Cu deposition at -0.05V, rinse with BE at -0.05V
3. Rinse with Pd^{2+} solution at OCP, SLRR at OCP



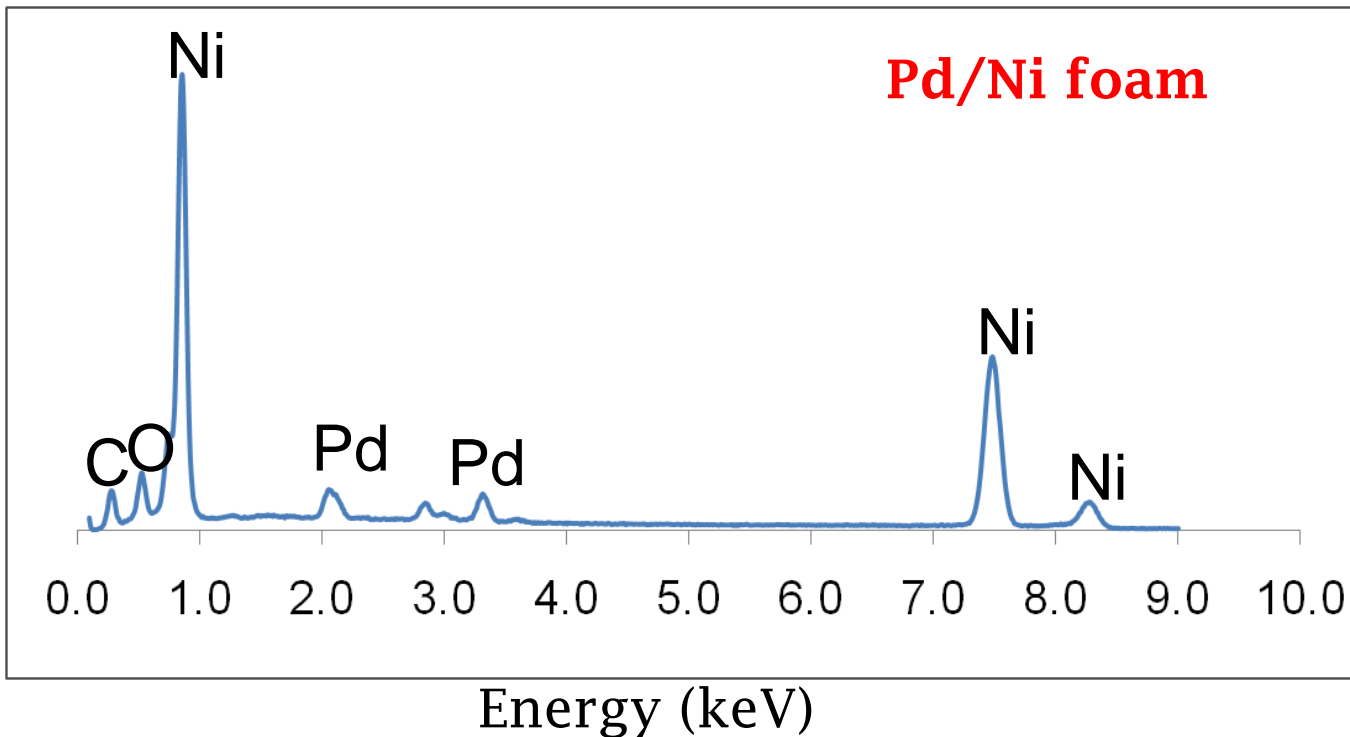
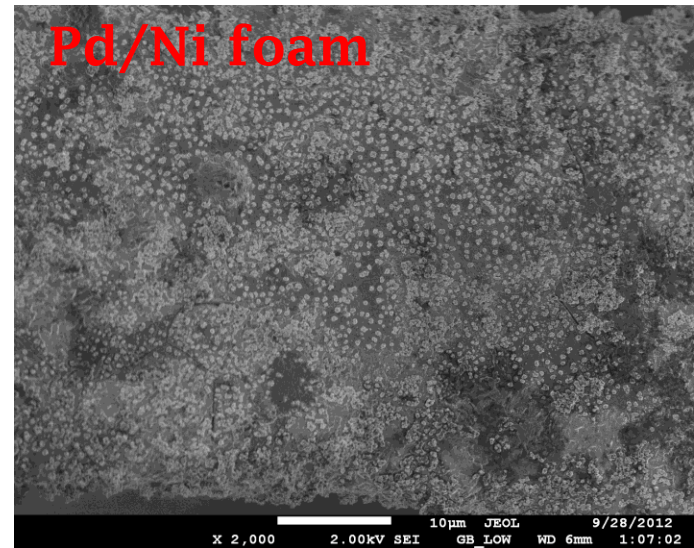
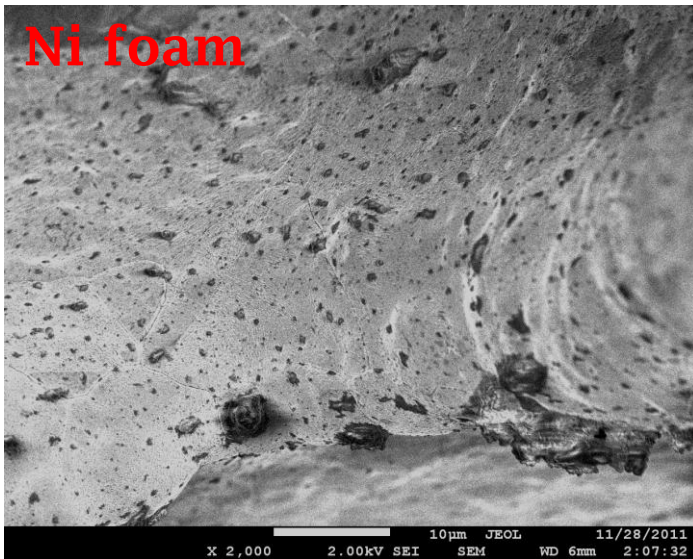
Pd/carbon paper: SEM, AFM micrographs and EDX profile



Energy (keV)

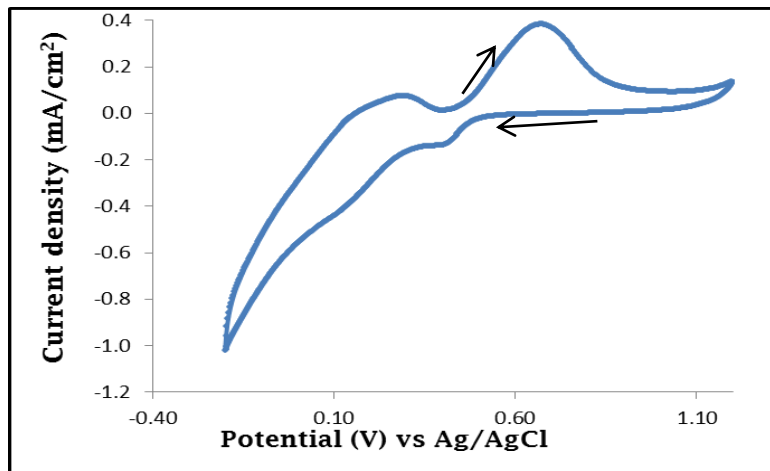
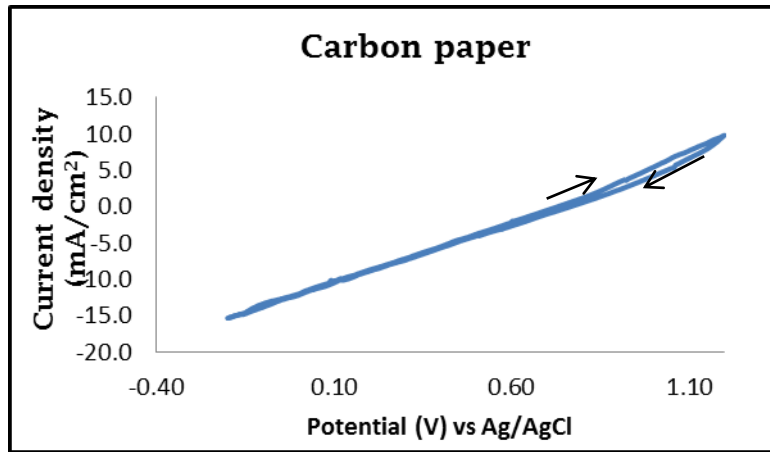


Pd/Ni foam: SEM micrographs and EDX profile

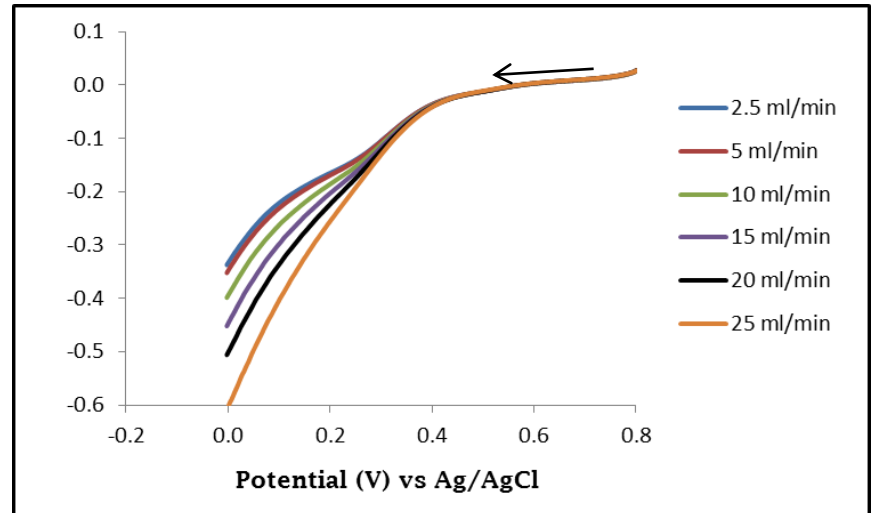


Pd/Carbon paper: Electrochemical Evaluation

(i) CV in 0.1 M HClO₄ + N₂ at 50 mV/s

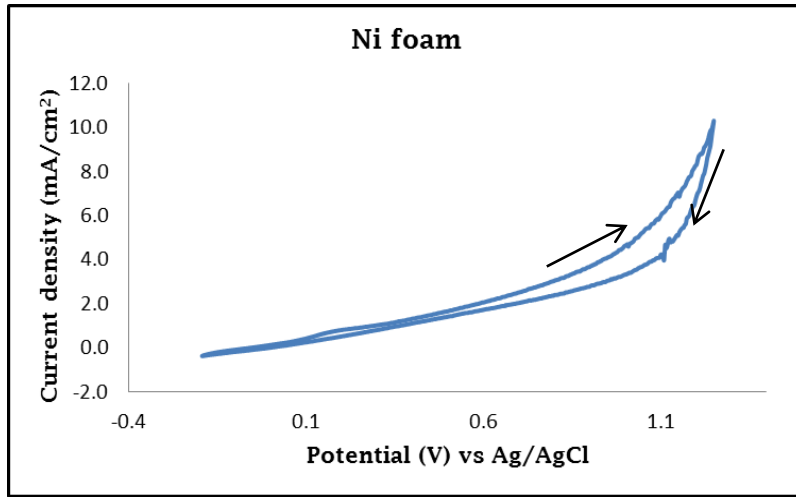


(ii) LSV in 0.1 M HClO₄ + O₂ at 10 mV/s

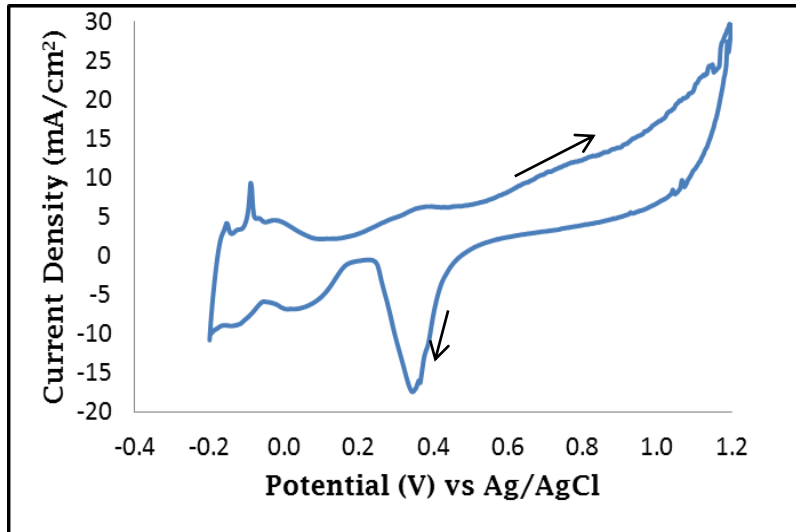
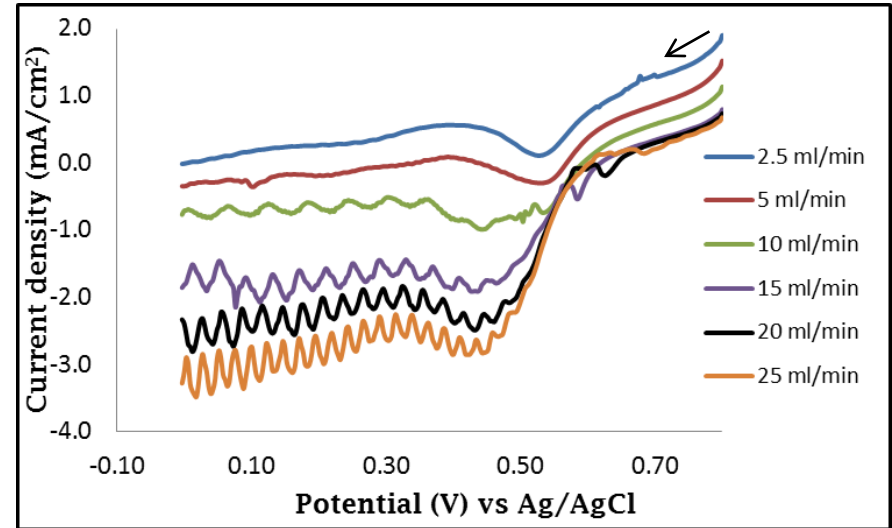


Pd/Ni foam: Electrochemical Evaluation

(i) CV in 0.1 M HClO₄ + N₂ at 100 mV/s

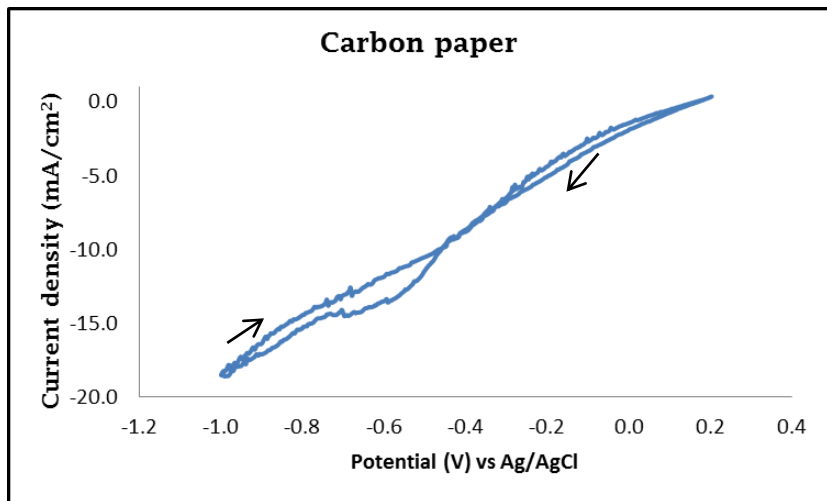


(ii) LSV in 0.1 M HClO₄ + O₂ at 10 mV/s

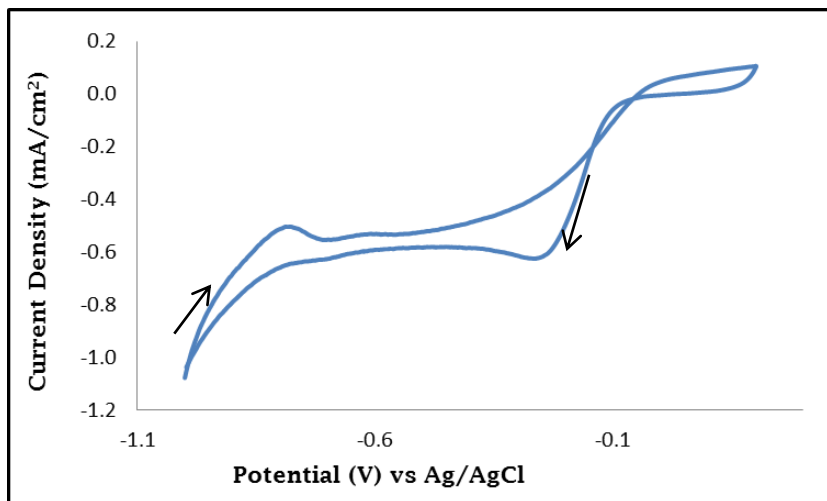
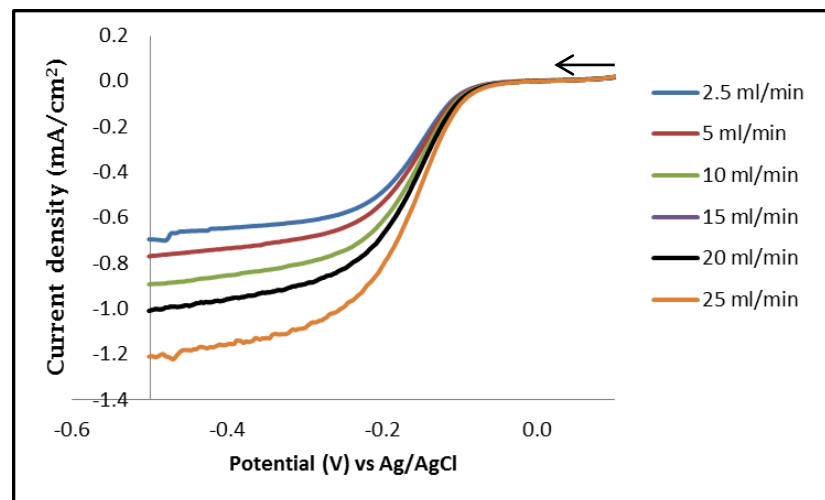


Pd/Carbon paper: Electrochemical Evaluation

(i) CV in 0.1 M KOH + N₂ at 50mV/s

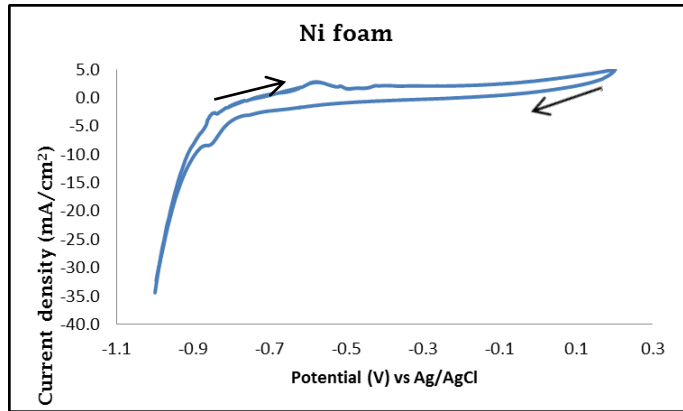


(ii) LSV in 0.1 M KOH + O₂ at 10mV/s

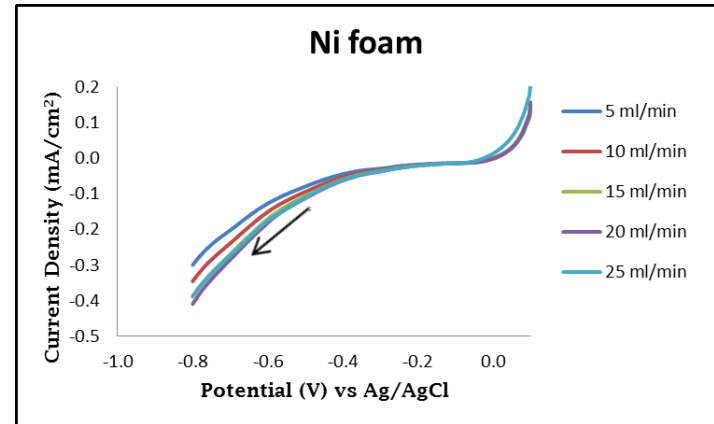


Pd/Ni foam: Electrochemical Evaluation

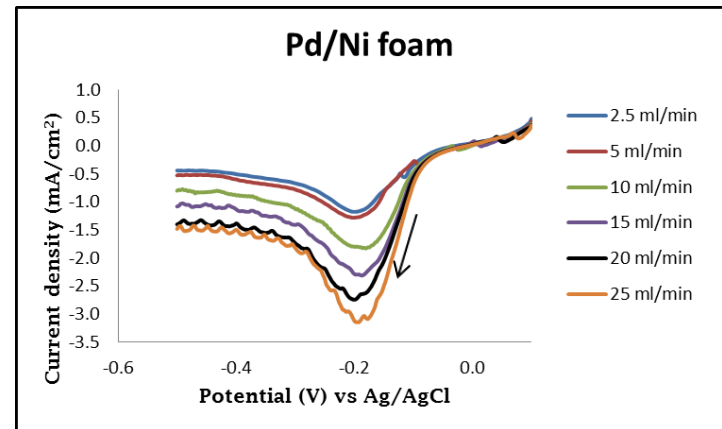
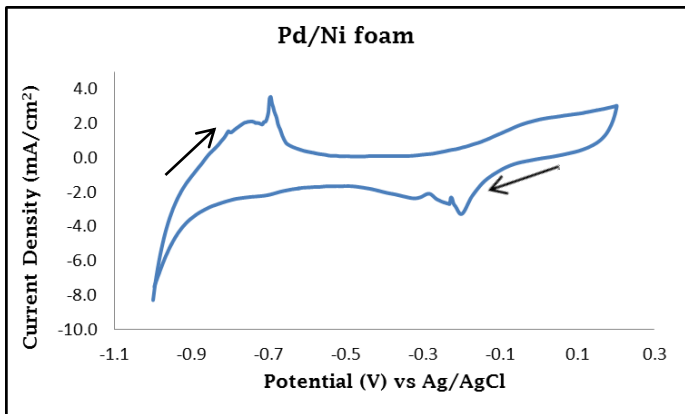
(i) CV in 0.1 M KOH + N₂ at 100 mV/s



(ii) LSV in 0.1 M KOH + O₂ at 10 mV/s



(i) CV in 0.1 M KOH + N₂ at 100 mV/s



Electrochemical evaluation: summary

at 15 ml/min

Electro-Catalyst	Onset potential (V) vs Ag/AgCl	Limiting current density (mA/cm ²)
Pd/C paper in acid	0.407	0.4492
Pd/Ni foam in acid	0.606	1.8862
Ni foam in alkaline	-0.508	0.400
Pd/C paper in alkaline	-0.073	0.880
Pd/Ni foam in alkaline	-0.052	2.2985

Conclusions

- Pd nanoclusters were successfully deposited using SLRR
- Pd distribution on substrates was not uniform
- Pd/Ni foam improved performance vs. carbon paper
 - More positive onset potential
 - High current density

Future Work

- Incorporate complexing agents (Chloride) for uniform distribution of Pd on substrates: slow the exchange rate
- Synthesize binary electrocatalysts: DMFC
- MEA fabrication and FC testing under active conditions
- Investigate other “sacrificial metals” that will allow UPD deposition on C-and Ni- based substrates

Acknowledgements

- Dr Mkhulu MATHE (EM Manager)
- Dr Kenneth OZOEMENA (EET research group leader)
- Ms. Eldah Louw
- *Mr. Charl Jafta*
- *Dr Lindiwe Khotseng (SAIAMC, UWC)*
- *National Centre for Nanostructured materials (NCNSM)*

Finances:

- **CSIR**
- **NRF**

THANK YOU